

ABSTRACT OF THE DISCLOSURE

A method for manufacturing an electronic component including the steps of preparing a pair of substantially round conductive wires, bending one end portion of each of the pair of conductive wires outward at an angle of about 90 degrees, forming a flat portion on each of the pair of substantially round conductive wires by press extending at least the portion on the tip side from the bending point so as to be extended substantially parallel to a lead portion of the lead terminal, such that a thickness of the flat portion is less than a diameter of each of the pair of substantially round conductive wires, forming a cup-shaped holder portion by bending the flat portion inwards, holding both end portions of a piezoelectric element in a pair of the cup-shaped holder portions, and electrically and mechanically connecting the cup-shaped holder portions and the electrodes formed in both end portions of the piezoelectric element by using a conductive joining material.